

**Test Data
For PMP7957
5/7/2013**

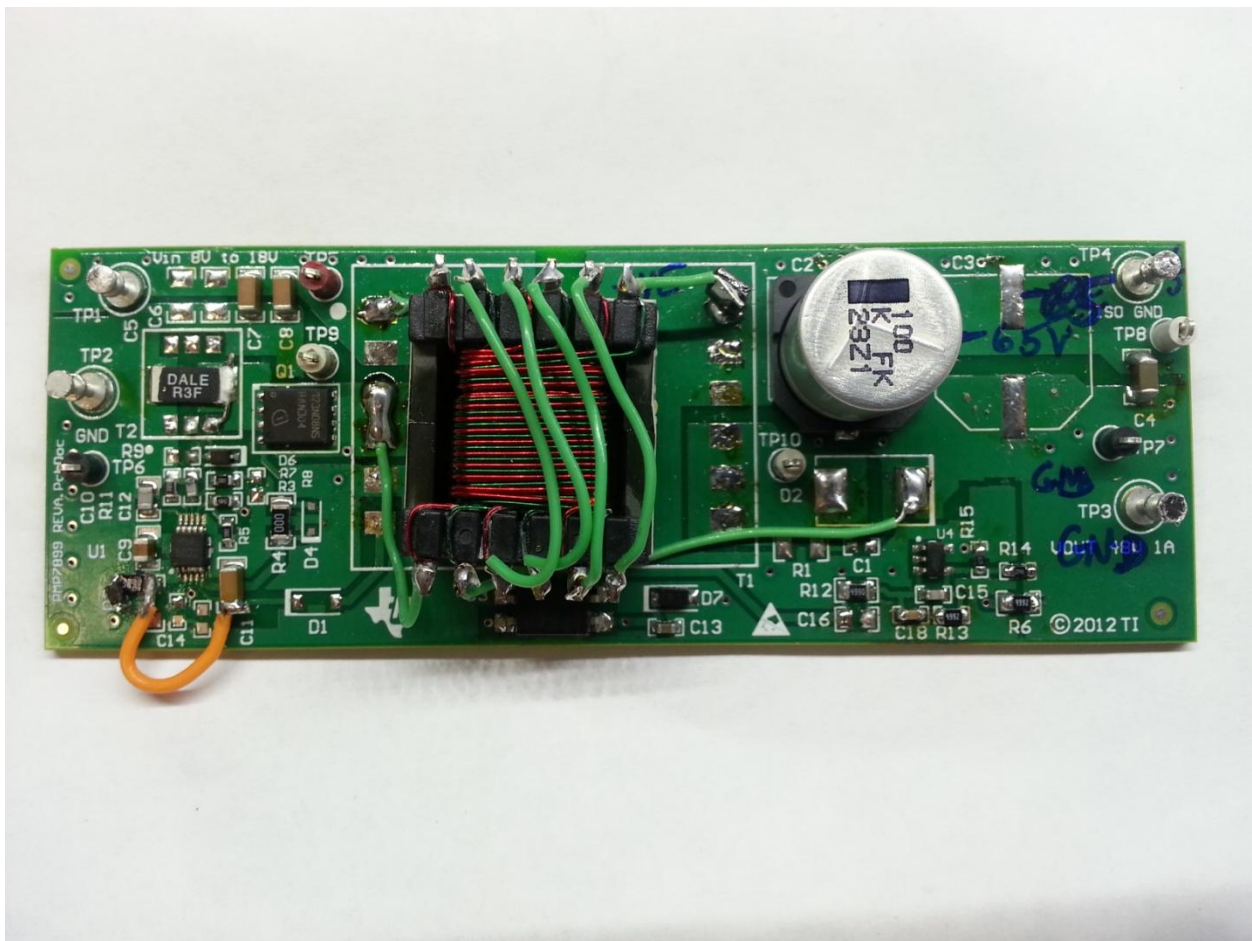


Test SPECIFICATIONS

Vin Min.	10V
Vin Max.	14V
Vin Nominal	12V
Vout	-65V
Iout	100mA Max.

FABRICATION

Board Dimensions: 1.4" x 4"



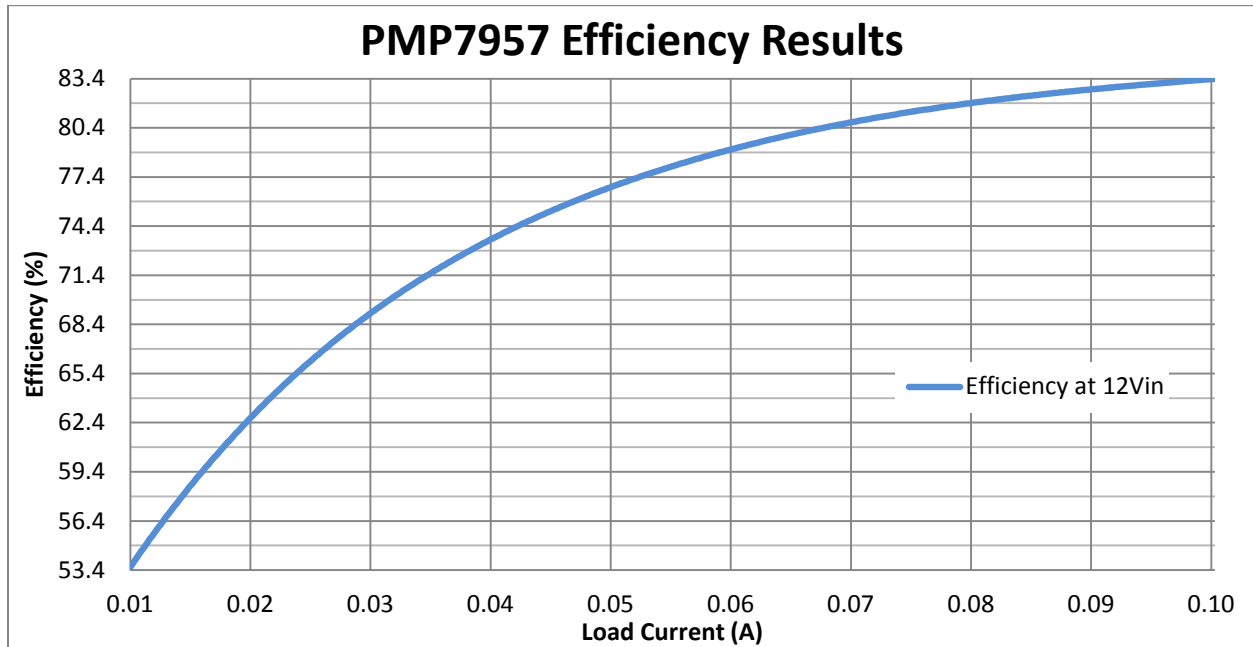
Thermal Data



IR thermal image taken at steady state at 100mA load and 12Vin. **Rsense (RC7) should be replaced either by two resistors in parallel or a higher power rated resistor.**

TYPICAL PERFORMANCE

EFFICIENCY

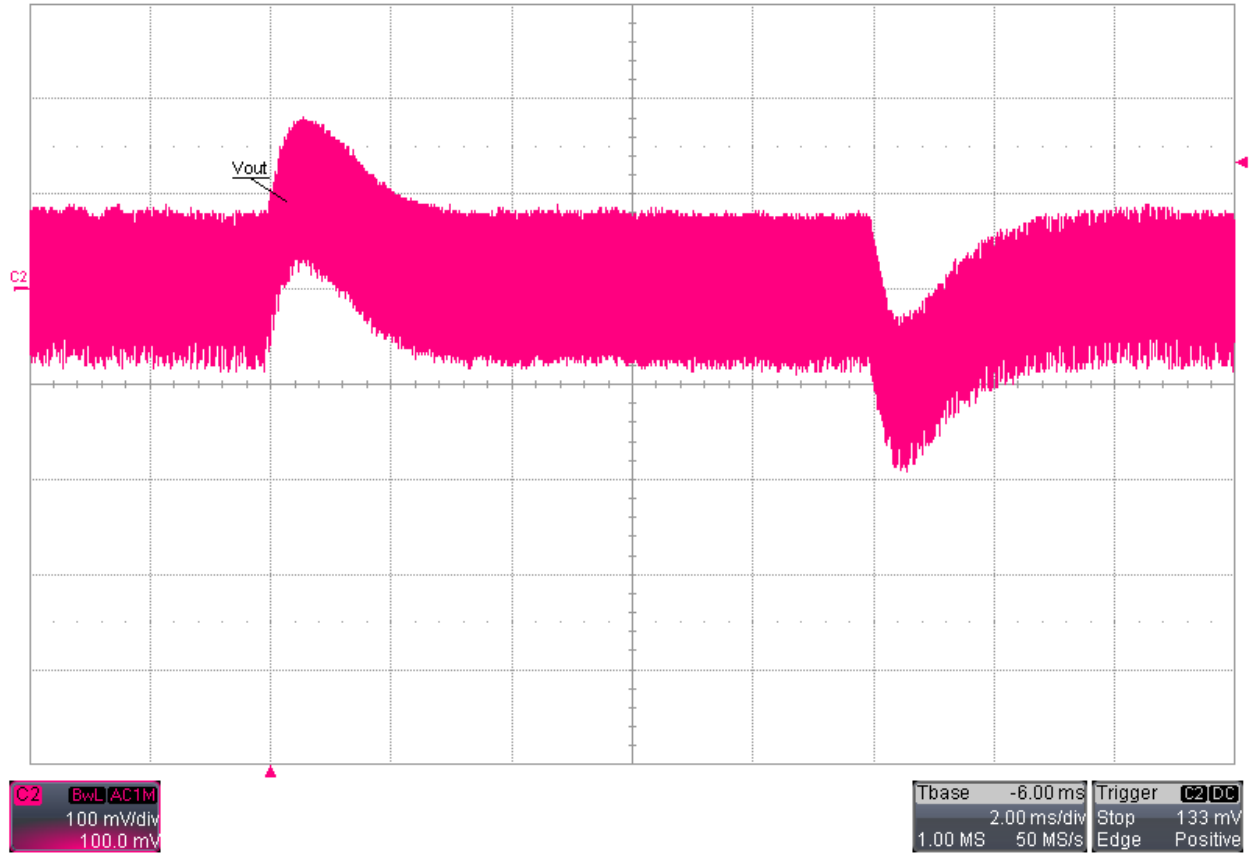


Efficiency Data

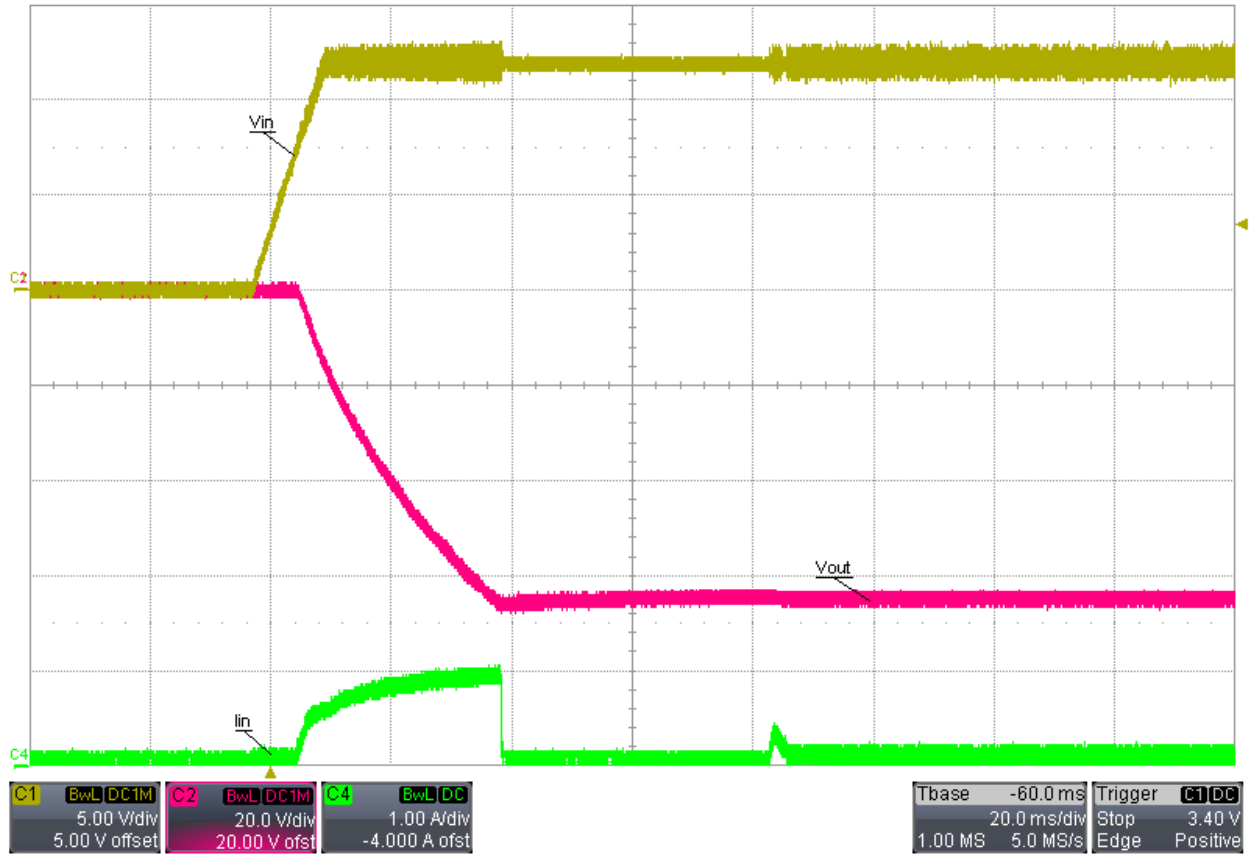
Vin (V)	Iin (A)	Vout (V)	Iout (A)	Pin (W)	Pout (W)	Efficiency (%)
11.998	0.1024	65.177	0.0101	1.229	0.658	53.6
12.006	0.15	65.177	0.02	1.801	1.304	72.4
11.998	0.2203	65.177	0.03	2.643	1.955	74.0
12.001	0.29	65.175	0.04	3.480	2.607	74.9
12.007	0.3553	65.174	0.0503	4.266	3.278	76.8
12.002	0.4139	65.174	0.0603	4.968	3.930	79.1
12.005	0.4726	65.174	0.0703	5.674	4.582	80.8
12.000	0.5322	65.174	0.0803	6.386	5.233	81.9
12.005	0.5924	65.175	0.0903	7.112	5.885	82.8
12.009	0.6534	65.176	0.1004	7.847	6.544	83.4

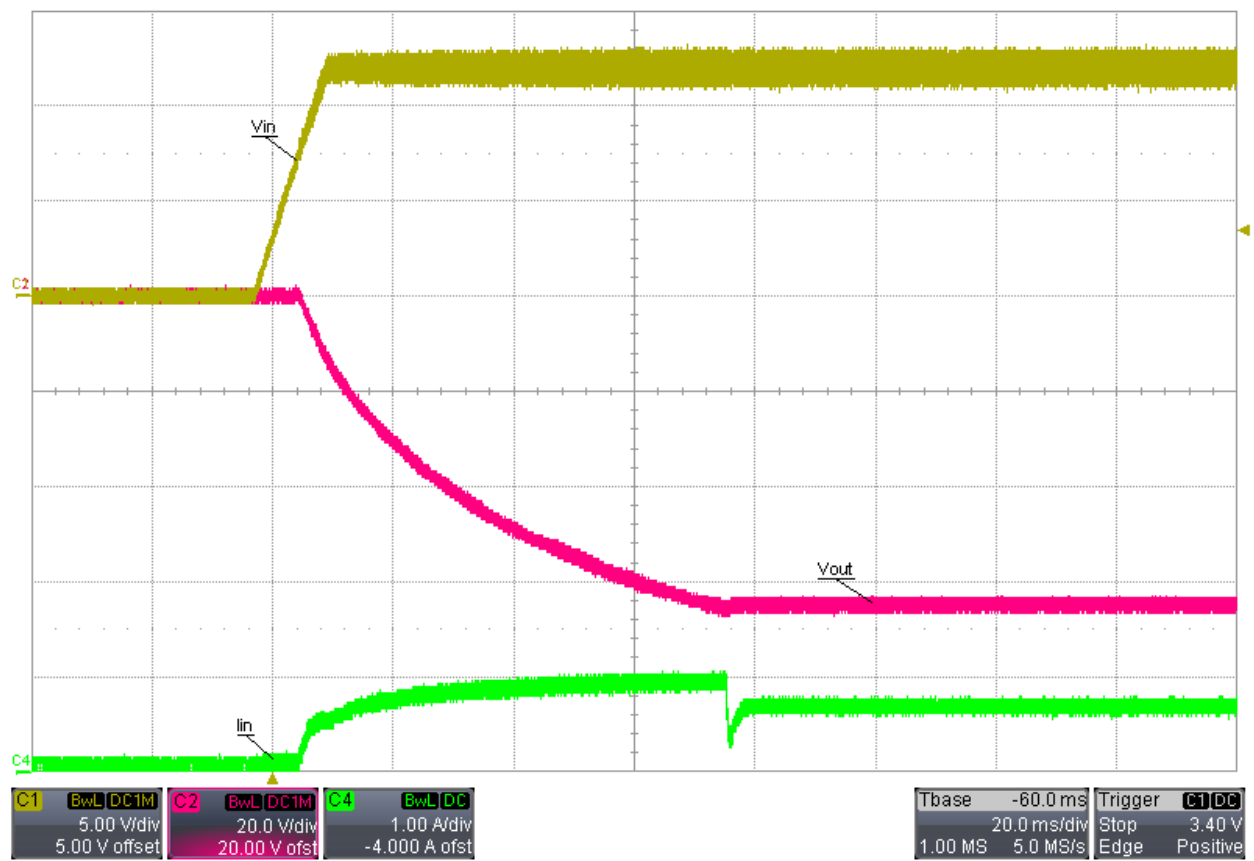
Waveforms

Load Transient Response



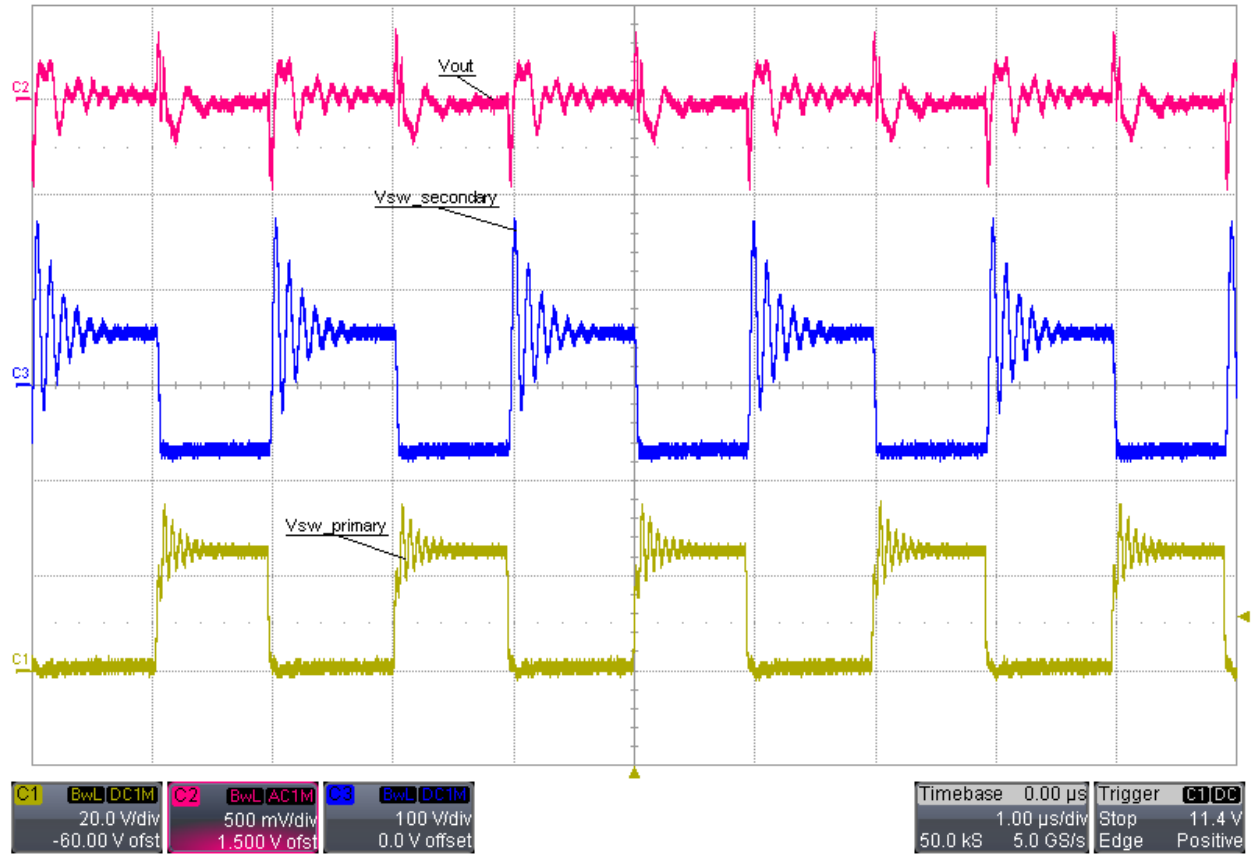
Load Transient Response at 12Vin 50%-to-100% Load Step (50mA-to-100mA)

Startup

Startup into No Load (12Vin)



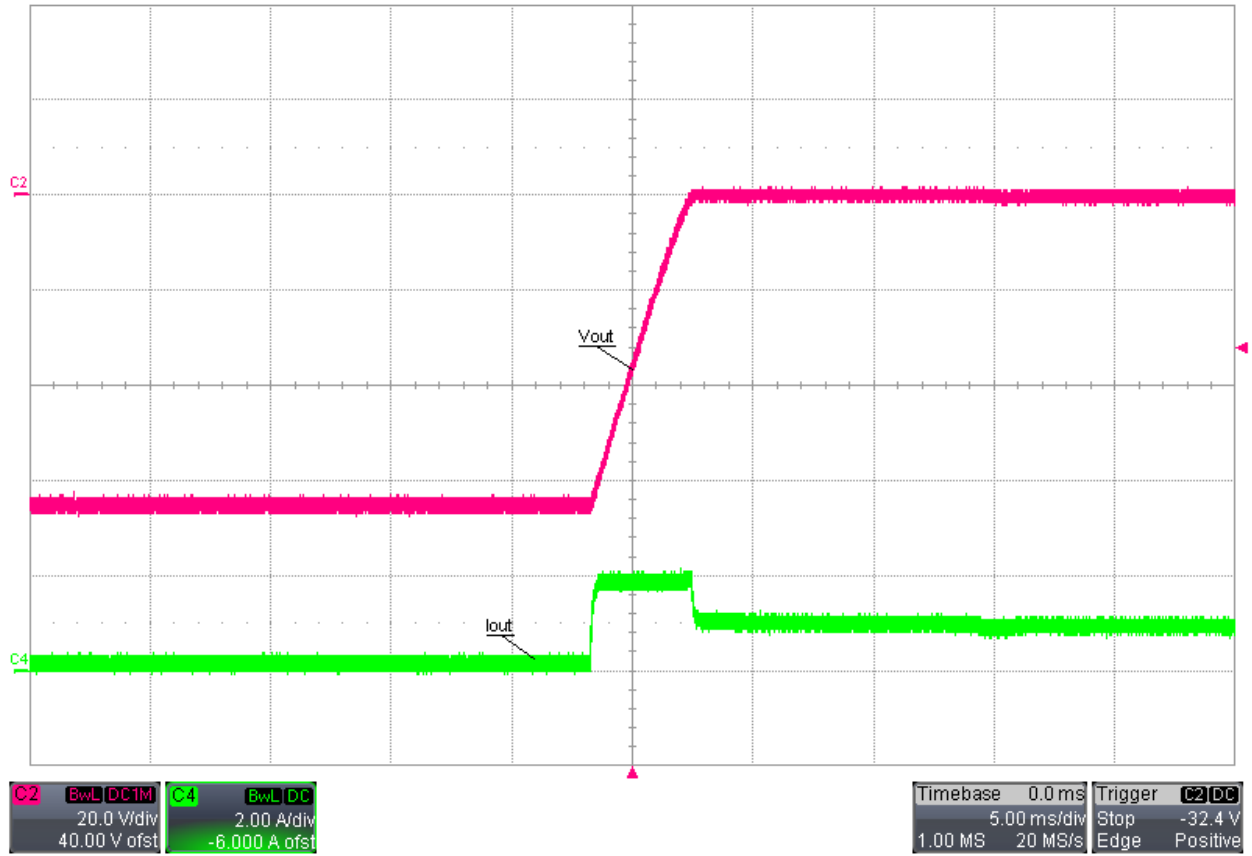
Startup into Full (100mA) Load (12Vin)

Output Voltage Ripple and Switch Node Voltage

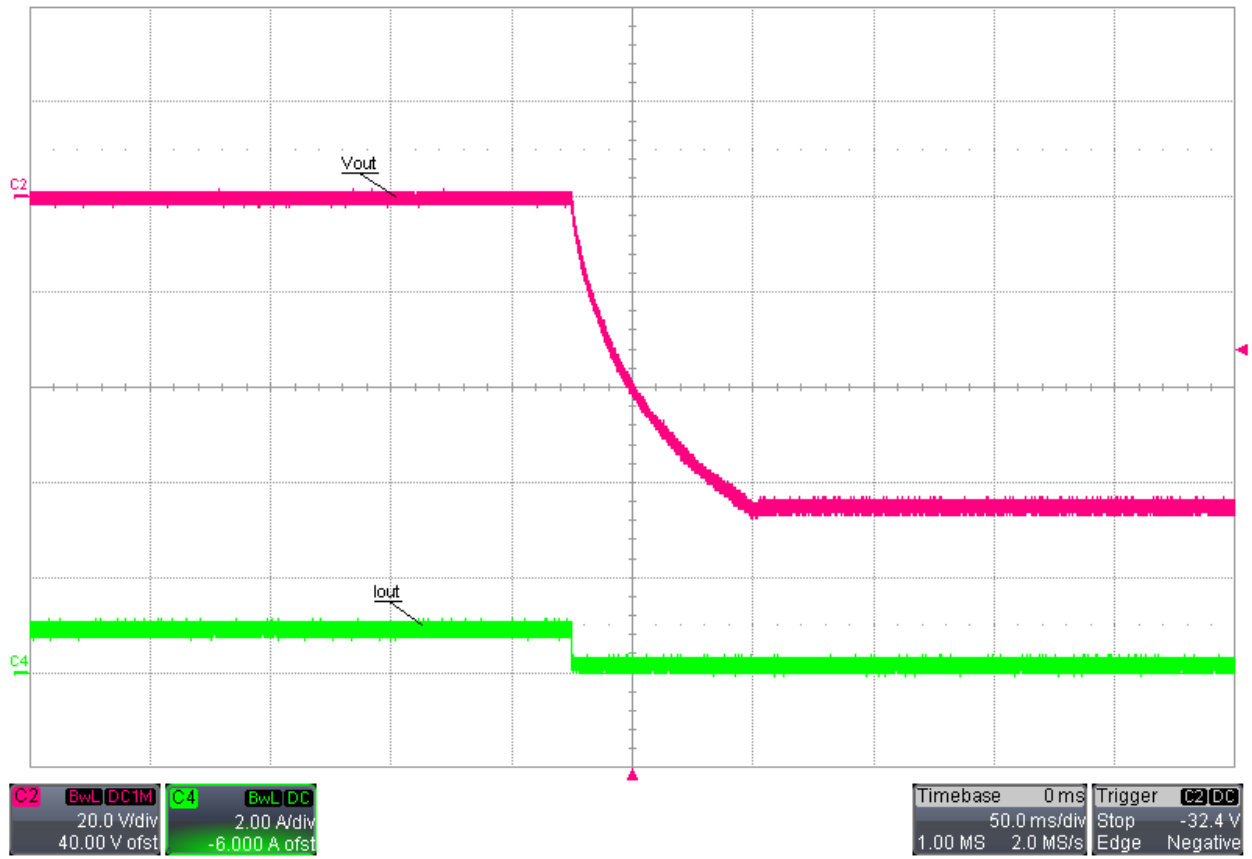


Output Voltage Ripple and Switch Node Voltage at 12Vin Full (100mA) Load (Vripple \approx 800mVp-p)

Short Circuit Testing



Short Circuit Applied at 12Vin



Short Circuit Recovery at 12Vin

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